

DESCRIPTION

The SSF2318E uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operate with gate voltages as low as 2.5V.

FEATURES

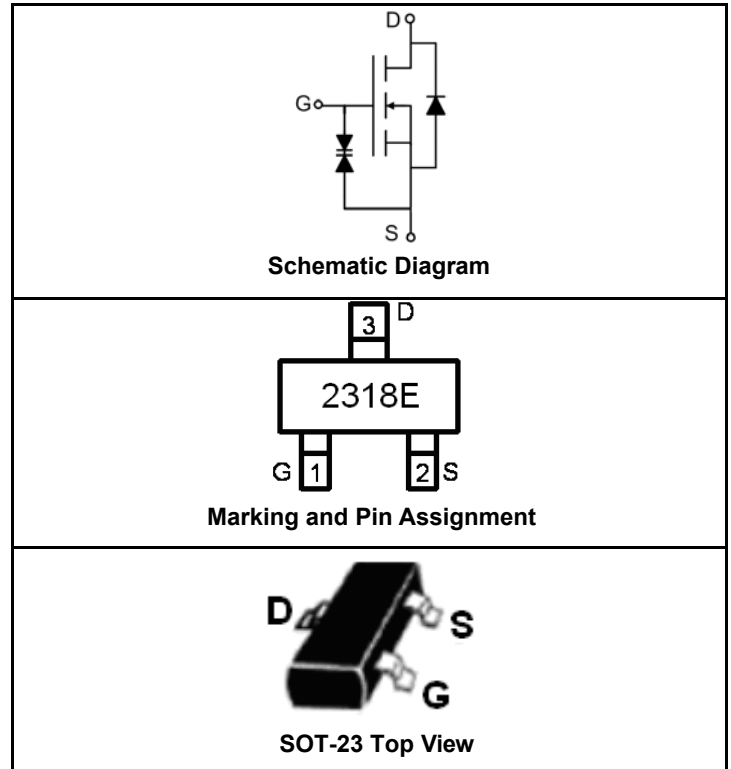
- $V_{DS} = 20V, I_D = 6.5A$
 $R_{DS(ON)} < 34m\Omega @ V_{GS}=1.8V$
 $R_{DS(ON)} < 26m\Omega @ V_{GS}=2.5V$
 $R_{DS(ON)} < 22m\Omega @ V_{GS}=4.5V$

ESD Rating: 2000V HBM

- High Power and Current Handling Capability
- Lead Free
- Surface Mount Package

APPLICATIONS

- Battery Protection
- Load Switch
- Power Management



PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2318E	SSF2318E	SOT-23	Ø330mm	12mm	3000 units

ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 8	V
Drain Current-Continuous@ Current-Pulsed (Note 1)	I_D	6.5	A
	I_{DM}	30	A
Maximum Power Dissipation	P_D	1.4	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ C$

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	90	$^\circ C/W$
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ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 4.5V, V_{DS}=0V$			± 1	μA
		$V_{GS}=\pm 8V, V_{DS}=0V$			± 10	μA
ON CHARACTERISTICS (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.4	0.6	1	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=6.5A$		18	22	$m\Omega$
		$V_{GS}=2.5V, I_D=5.5A$		24	30	$m\Omega$
		$V_{GS}=1.8V, I_D=5A$		40	55	$m\Omega$
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_D=6.5A$		7		S
DYNAMIC CHARACTERISTICS (Note 4)						
Input Capacitance	C_{iss}	$V_{DS}=10V, V_{GS}=0V,$ $F=1.0MHz$		1160		PF
Output Capacitance	C_{oss}			200		PF
Reverse Transfer Capacitance	C_{rss}			140		PF
SWITCHING CHARACTERISTICS (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V, I_D=1A$ $V_{GS}=5V, R_{GEN}=3\Omega$		6.5		nS
Turn-on Rise Time	t_r			13		nS
Turn-Off Delay Time	$t_{d(off)}$			50		nS
Turn-Off Fall Time	t_f			30		nS
Total Gate Charge	Q_g	$V_{DS}=10V, I_D=6.5A,$ $V_{GS}=4.5V$		10		nC
Gate-Source Charge	Q_{gs}			2.3		nC
Gate-Drain Charge	Q_{gd}			3		nC
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode Forward Voltage (Note 3)	V_{SD}	$V_{GS}=0V, I_S=1A$		0.76	1	V

NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production testing.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

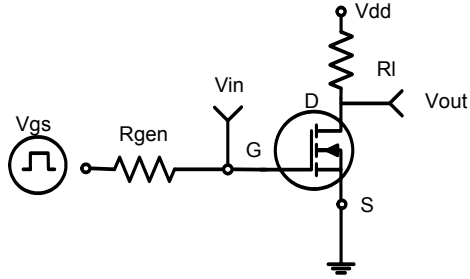


Figure 1. Switching Test Circuit

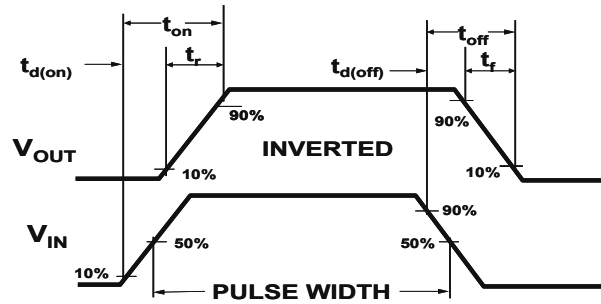


Figure 2. Switching Waveforms

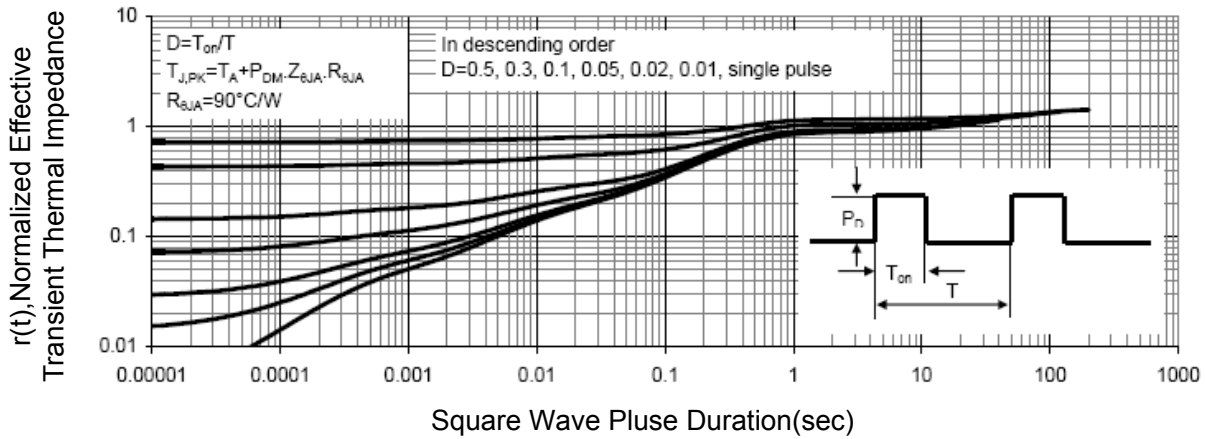
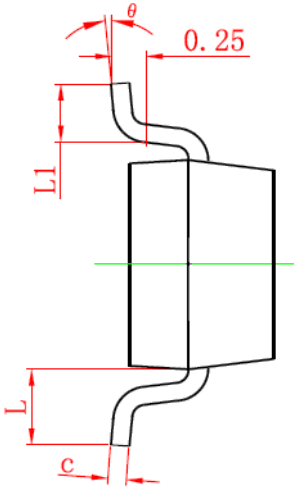
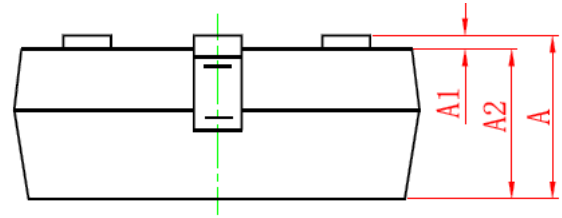
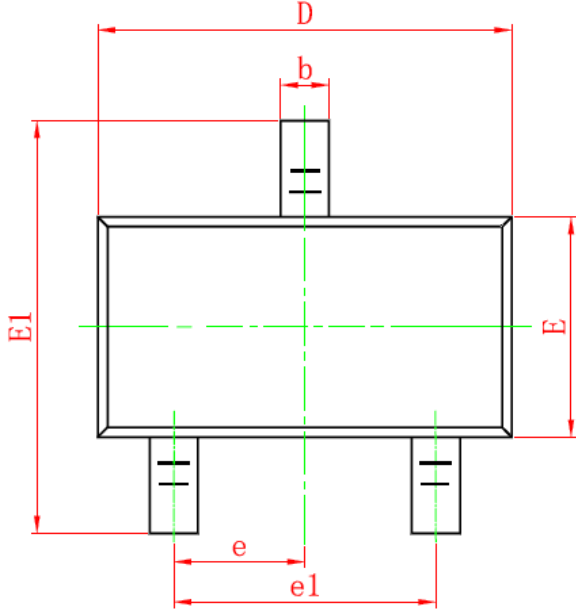


Figure 3. Normalized Maximum Transient Thermal Impedance

SOT-23 PACKAGE INFORMATION

Dimensions in Millimeters (UNIT:mm)



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

NOTES

1. All dimensions are in millimeters.
2. Tolerance ±0.10mm (4 mil) unless otherwise specified.
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.